**Product / Process Change Notice**

**Parts Affected:**

Chip process CP206, N-Channel Field Effect Transistors, wafers, and bare die.

**Extent of Change:**

The CP206 wafer process has been discontinued and replaced with the CP216 wafer process. See figures 1 and 2 for details.

**Reason for Change:**

This process was transferred to an alternate wafer foundry which provides improved and consistent yields.

**Effect of Change:**

The wafer process meets all electrical specifications of the individual devices listed on the following page.

**Qualification:**

|  |  |  |
| --- | --- | --- |
| **Test** | **Condition** | **Failure rate** |
| **Resistance to Solder Shock**  | T =260°C ±5°CDwell time = 10 sec.**JESD22-B106** | 0/77 |
| **High Temperature Storage Life/ bake test.** |  150°C (-0/+10)°C, 1000 hours.**JESD22-A103** | 0/77 |
| **Temperature Cycling** | T= -65°C to +150°C1000 cycles. Dwell time = 15 min.**JESD22-A104** | 0/77 |
| **High Temperature Reverse Bias (HTRB)** | T=125°C, t=1000 hours, VR=VZ**JESD22-A108** | 0/77 |
| **Highly Accelerated Temperature and Humidity Stress Test (HAST)** | T = 130°C, RH = 85%, P = 33.3 psia, and t = 96 hours.Bias conditions per device specification sheet.**JESD22-A110** | 0/77 |
| **Accelerated Moisture Resistance Unbiased Autoclave** | Temperature = 121°C ± 2°C; relative humidity = 100%; vapor pressure = 29.7 psia (15psig). t=96 hours**JESD22-A102** | 0/77 |

**Effective Date of Change:**

April 16, 2018 - Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact Salesperson or Manufacturer’s Representative.

**Figure 1: CP206 Chip Geometry (Discontinued) Figure 2: CP216 Chip Geometry**

  

Wafer Diameter: 5 inch

Die Size: 21 x 18 mils

Die Thickness: 8.0 mils

Bond Pad Size (Drain): 3.0 x 3.0 mils

Bond Pad Size (Source): 3.0 x 3.0 mils

Bond Pad Size (Gate): 3.0 x 3.0 mils

Topside Metal: Al (30,000Å)

Backside Metal: Au (6,000Å)

Wafer Diameter: 4 inch

Die Size: 21 x 16 mils

Die Thickness: 7.9 mils

Bond Pad Size (Drain): 3.3 x 4.5 mils

Bond Pad Size (Source): 3.3 x 4.5 mils

Topside Metal: Al (10,000Å)

Backside Metal: Au (3,250Å)

**Part Numbers Affected:**

|  |  |
| --- | --- |
| 2N4391 | CP206-2N4391-CT |
| 2N4392 | CP206-2N4391-WN |
| 2N4393 | CP206-2N4392-CM |
| 2N4092 | CP206-2N4392-CT |
| 2N4861 | CP206-2N4392-WN |
| 2N4861A | CP206-2N4393-CT |
| CMPF4391 | CP206-2N4393-WN |
| CMPF4392 |   |
| CMPF4393 |   |

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

|  |  |
| --- | --- |
| Company Name: |  |
| Address: |  |
|  |
|  |
| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |